



# Model : CBAG0023231000-01

## BGA Heat Sink Specification

For 23x23 Chip set

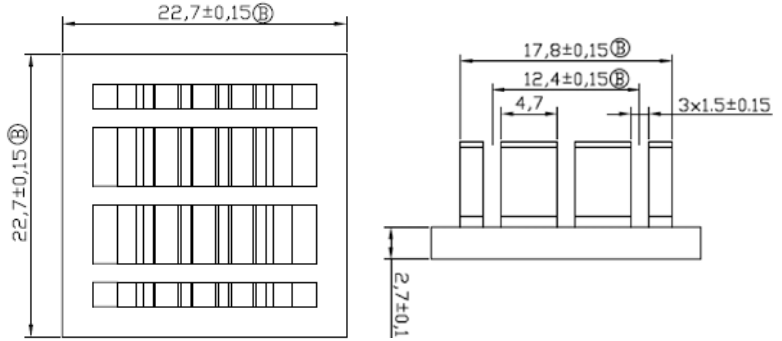


1. Material : Al 6063

2. Dimension :  
Foot print : 23x23mm  
Height : 10 mm  
Base (thickness) : 2.7 mm

3. Finish: Black Anodize

4. Accessory :  
Clip : Plastic (UL94-V0)  
Thermal pad : 8612I or others



## Performance

Heat Source (LxW)	15x15
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